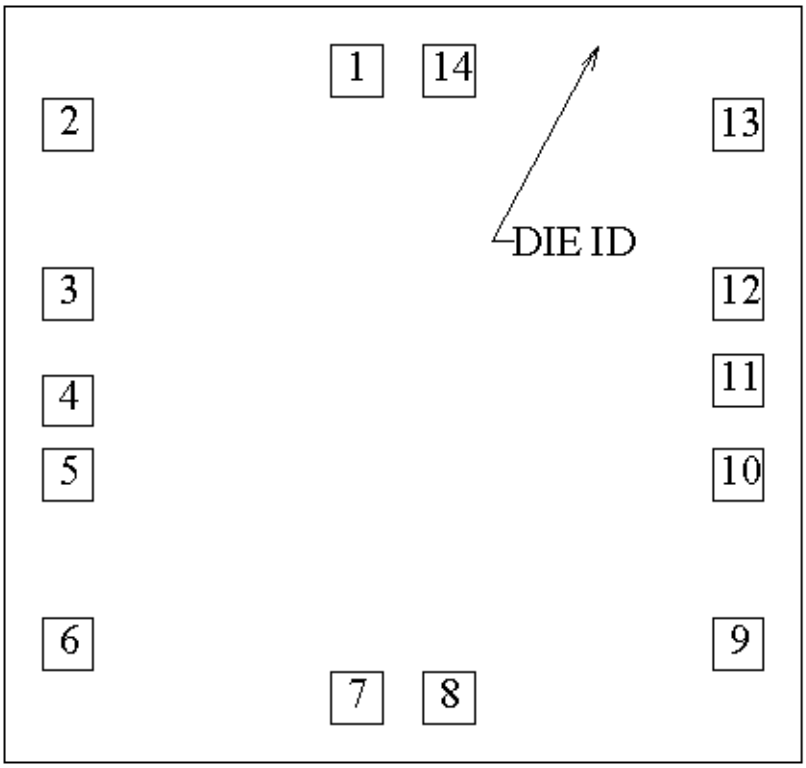
LM124 MD8 MW8
LOW POWER QUAD OPERATIONAL AMPLIFIER

September 16,2002

DIE LAYOUT (H-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		**General Die Information**	
Physical Die Identification	1902H	Bond Pad Opening Size (min)	92µm x 92µm
Die Step	H	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1422µm x 1346µm 56mils x 53mils	Back Side Connection	Floating or GND
Thickness	330µm Nominal		
Min Pitch	127µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (H -Step)

(Referenced to die center, coordinates in µm) NC = No Connection

SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES X	Y	PAD SIZE X		Y
Output 1	1	-82	559	92	x	92
Input 1-	2	-597	461	92	x	92
Input 1+	3	-597	161	92	x	92
V+	4	-597	-29	92	x	92
Input 2+	5	-597	-161	92	x	92
Input 2-	6	-597	-461	92	x	92
Output 2	7	-82	-559	92	x	92
Output 3	8	82	-559	92	x	92
Input 3-	9	597	-461	92	x	92
Input 3+	10	597	-161	92	x	92
Gnd	11	597	7	92	x	92
Input 4+	12	597	161	92	x	92
Input 4-	13	597	461	92	x	92
Output 4	14	82	559	92	x	92

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